



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPTG025N08NM5	Issued	24. June 2021
MA#	MA005552474		
Package	PG-HSOG-8-1	Weight*	703.00 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.149	0.45	0.45	4479	4479
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.09	19.12	190924	191172
wire	non noble metal	aluminium	7429-90-5	11.955	1.70	1.70	17005	17005
encapsulation	inorganic material	zinc oxide	1314-13-2	2.661	0.38		3785	
	miscellaneous	miscellaneous	-	10.644	1.51		15140	
	plastics	epoxy resin	-	39.913	5.68		56776	
	inorganic material	silicon dioxide	60676-86-0	212.870	30.28	37.85	302803	378504
lead finish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11819	11819
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	312	313
solder	non noble metal	tin	7440-31-5	0.056	0.01		80	
	noble metal	silver	7440-22-4	0.071	0.01		100	
	non noble metal	lead	7439-92-1	2.694	0.38	0.40	3832	4012
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		118	
	non noble metal	iron	7439-89-6	0.276	0.04		393	
	non noble metal	copper	7440-50-8	275.705	39.22	39.27	392185	392696
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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